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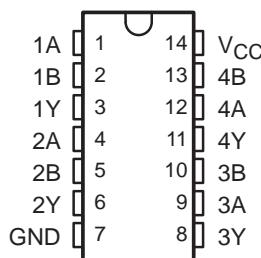
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SN54ACT08, SN74ACT08 QUADRUPLE 2-INPUT POSITIVE-AND GATES

SCAS535C – SEPTEMBER 1995 – REVISED OCTOBER 2003

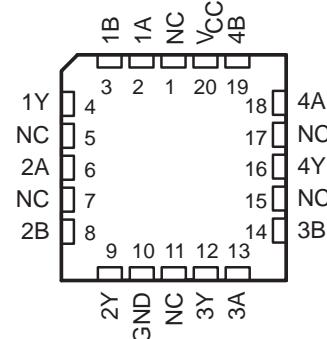
- 4.5-V to 5.5-V V_{CC} Operation
- Inputs Accept Voltages to 5.5 V

SN54ACT08 . . . J OR W PACKAGE
 SN74ACT08 . . . D, DB, N, NS, OR PW PACKAGE
 (TOP VIEW)



- Max t_{pd} of 10 ns at 5 V
- Inputs Are TTL-Voltage Compatible

SN54ACT08 . . . FK PACKAGE
 (TOP VIEW)



NC – No internal connection

description/ordering information

The 'ACT08 devices are quadruple 2-input positive-AND gates. These devices perform the Boolean functions $Y = A \bullet B$ or $Y = \bar{A} + \bar{B}$ in positive logic.

ORDERING INFORMATION

T_A	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	PDIP – N	Tube	SN74ACT08N	SN74ACT08N
	SOIC – D	Tube	SN74ACT08D	ACT08
		Tape and reel	SN74ACT08DR	
	SOP – NS	Tape and reel	SN74ACT08NSR	ACT08
	SSOP – DB	Tape and reel	SN74ACT08DBR	AD08
	TSSOP – PW	Tube	SN74ACT08PW	AD08
		Tape and reel	SN74ACT08PWR	
-55°C to 125°C	CDIP – J	Tube	SNJ54ACT08J	SNJ54ACT08J
	CFP – W	Tube	SNJ54ACT08W	SNJ54ACT08W
	LCCC – FK	Tube	SNJ54ACT08FK	SNJ54ACT08FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each gate)

INPUTS		OUTPUT
A	B	Y
H	H	H
L	X	L
X	L	L



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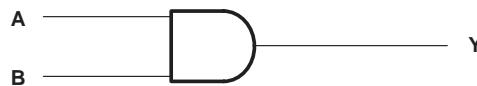
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 On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

SN54ACT08, SN74ACT08 QUADRUPLE 2-INPUT POSITIVE-AND GATES

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logic diagram, each gate (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	-0.5 V to 7 V	
Input voltage range, V_I (see Note 1)	-0.5 V to V_{CC} + 0.5 V	
Output voltage range, V_O (see Note 1)	-0.5 V to V_{CC} + 0.5 V	
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	± 20 mA	
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	± 20 mA	
Continuous output current, I_O ($V_O = 0$ to V_{CC})	± 50 mA	
Continuous current through V_{CC} or GND	± 200 mA	
Package thermal impedance, θ_{JA} (see Note 2): D package	86°C/W	
DB package	96°C/W	
N package	80°C/W	
NS package	76°C/W	
PW package	113°C/W	
Storage temperature range, T_{STG}	-65°C to 150°C	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

	SN54ACT08		SN74ACT08		UNIT
	MIN	MAX	MIN	MAX	
V_{CC} Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH} High-level input voltage	2		2		V
V_{IL} Low-level input voltage			0.8	0.8	V
V_I Input voltage	0	V_{CC}	0	V_{CC}	V
V_O Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH} High-level output current		-24		-24	mA
I_{OL} Low-level output current		24		24	mA
$\Delta t/\Delta v$ Input transition rise or fall rate		8		8	ns/V
T_A Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN54ACT08, SN74ACT08
QUADRUPLE 2-INPUT POSITIVE-AND GATES

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			SN54ACT08		SN74ACT08		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = -50 µA	4.5 V	4.4	4.49		4.4		4.4		V
		5.5 V	5.4	5.49		5.4		5.4		
	I _{OH} = -24 mA	4.5 V	3.86			3.7		3.76		
		5.5 V	4.86			4.7		4.76		
	I _{OH} = -50 mA [†]	5.5 V				3.85				
		5.5 V						3.85		
	I _{OL} = 50 µA	4.5 V	0.001	0.1		0.1		0.1		V
		5.5 V	0.001	0.1		0.1		0.1		
V _{OL}	I _{OL} = 24 mA	4.5 V		0.36		0.5		0.44		
		5.5 V		0.36		0.5		0.44		
	I _{OL} = 50 mA [†]	5.5 V				1.65				
		5.5 V						1.65		
I _I	V _I = V _{CC} or GND	5.5 V		±0.1		±1		±1		µA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V		2		80		20		µA
ΔI _{CC} [‡]	One input at 3.4 V, Other inputs at GND or V _{CC}	5.5 V		0.6		1.6		1.5		mA
C _i	V _I = V _{CC} or GND	5 V		4.5						pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.

[‡] This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.

**switching characteristics over recommended operating free-air temperature range,
 V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T _A = 25°C			SN54ACT08		SN74ACT08		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A or B	Y	1	6.5	9	1	10	1	10	ns
			1	6.5	9	1	10	1	10	

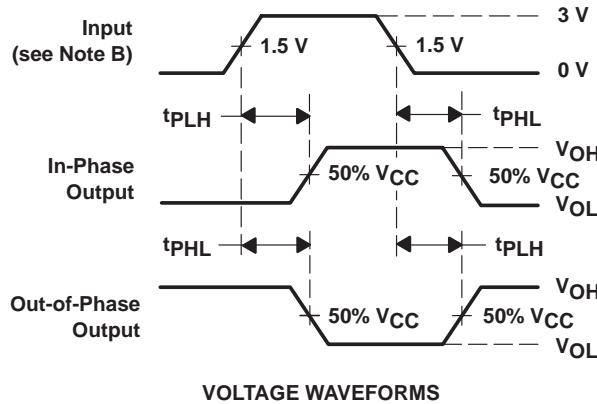
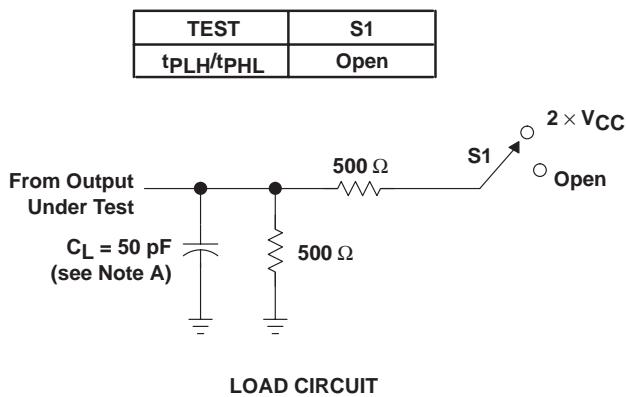
operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd} Power dissipation capacitance	C _L = 50 pF, f = 1 MHz	20	pF

SN54ACT08, SN74ACT08 QUADRUPLE 2-INPUT POSITIVE-AND GATES

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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-89547022A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962-89547022A SNJ54ACT08FK	Samples
5962-8954702CA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8954702CA SNJ54ACT08J	Samples
5962-8954702DA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8954702DA SNJ54ACT08W	Samples
SN74ACT08D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT08	Samples
SN74ACT08DBLE	OBsolete	SSOP	DB	14		TBD	Call TI	Call TI	-40 to 85		
SN74ACT08DBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AD08	Samples
SN74ACT08DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT08	Samples
SN74ACT08DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT08	Samples
SN74ACT08DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	-40 to 85	ACT08	Samples
SN74ACT08DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT08	Samples
SN74ACT08DRG3	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	ACT08	Samples
SN74ACT08DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT08	Samples
SN74ACT08N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74ACT08N	Samples
SN74ACT08NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT08	Samples
SN74ACT08PW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AD08	Samples
SN74ACT08PWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AD08	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ACT08PWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AD08	Samples
SN74ACT08PWLE	OBsolete	TSSOP	PW	14		TBD	Call TI	Call TI	-40 to 85		
SN74ACT08PWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	-40 to 85	AD08	Samples
SN74ACT08PWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AD08	Samples
SN74ACT08PWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AD08	Samples
SNJ54ACT08FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962-89547022A SNJ54ACT08FK	Samples
SNJ54ACT08J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8954702CA SNJ54ACT08J	Samples
SNJ54ACT08W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8954702DA SNJ54ACT08W	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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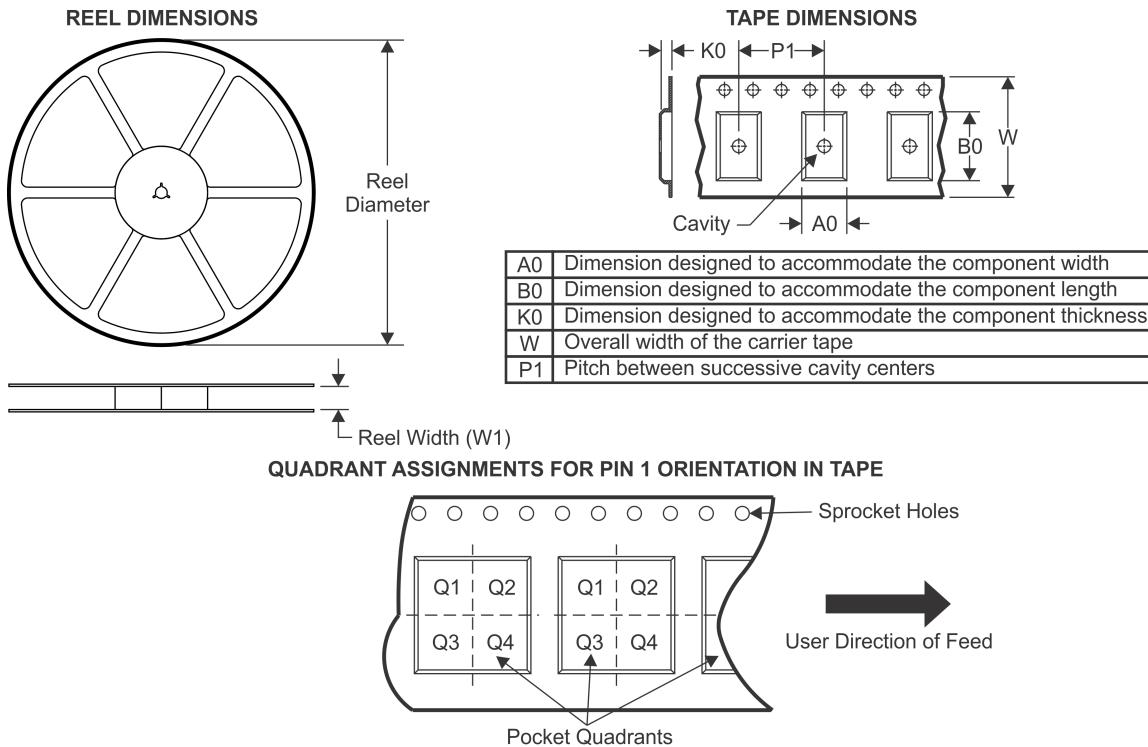
OTHER QUALIFIED VERSIONS OF SN54ACT08, SN74ACT08 :

- Catalog: [SN74ACT08](#)
- Enhanced Product: [SN74ACT08-EP](#), [SN74ACT08-EP](#)
- Military: [SN54ACT08](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications

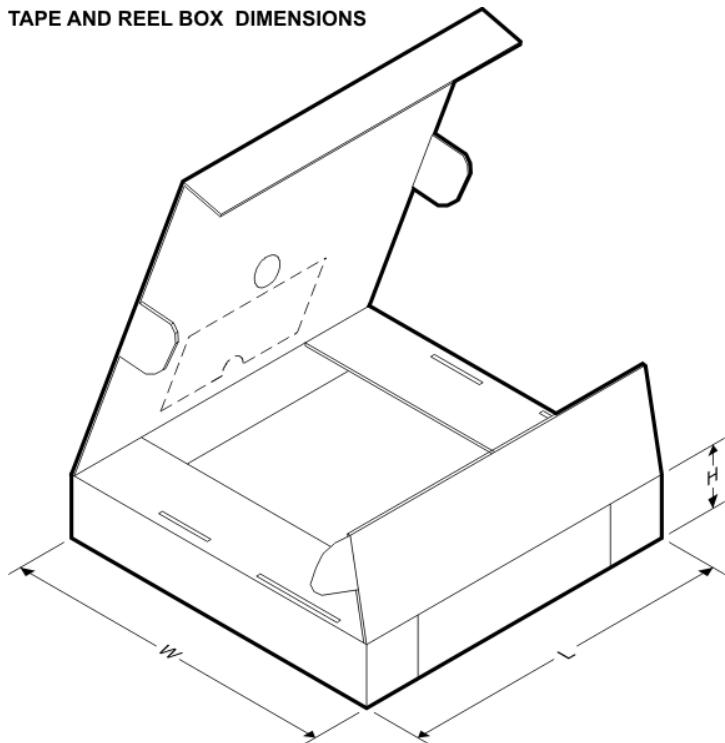
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ACT08DBR	SSOP	DB	14	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74ACT08DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74ACT08DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74ACT08DR	SOIC	D	14	2500	330.0	16.8	6.5	9.5	2.3	8.0	16.0	Q1
SN74ACT08DRG3	SOIC	D	14	2500	330.0	16.8	6.5	9.5	2.3	8.0	16.0	Q1
SN74ACT08DRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74ACT08DRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74ACT08NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74ACT08PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74ACT08PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74ACT08PWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



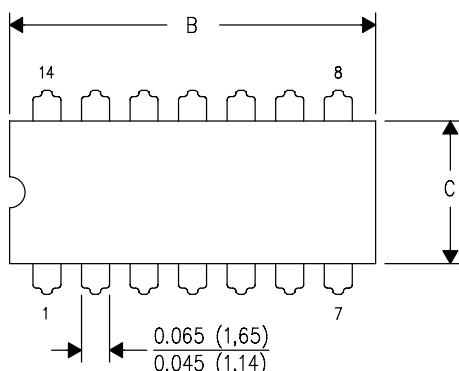
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ACT08DBR	SSOP	DB	14	2000	367.0	367.0	38.0
SN74ACT08DR	SOIC	D	14	2500	367.0	367.0	38.0
SN74ACT08DR	SOIC	D	14	2500	333.2	345.9	28.6
SN74ACT08DR	SOIC	D	14	2500	364.0	364.0	27.0
SN74ACT08DRG3	SOIC	D	14	2500	364.0	364.0	27.0
SN74ACT08DRG4	SOIC	D	14	2500	333.2	345.9	28.6
SN74ACT08DRG4	SOIC	D	14	2500	367.0	367.0	38.0
SN74ACT08NSR	SO	NS	14	2000	367.0	367.0	38.0
SN74ACT08PWR	TSSOP	PW	14	2000	364.0	364.0	27.0
SN74ACT08PWR	TSSOP	PW	14	2000	367.0	367.0	35.0
SN74ACT08PWRG4	TSSOP	PW	14	2000	367.0	367.0	35.0

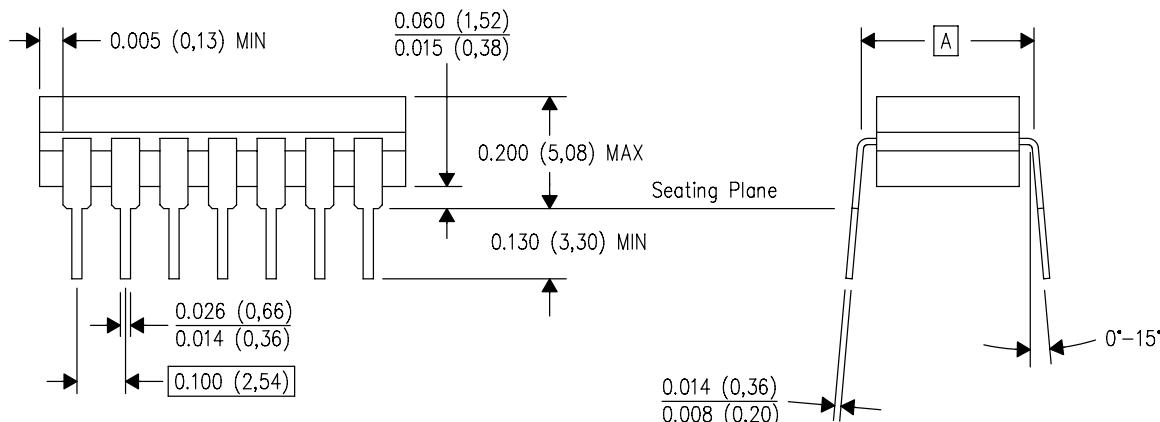
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM	PINS **	14	16	18	20
		A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX		0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN		—	—	—	—
C MAX		0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN		0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



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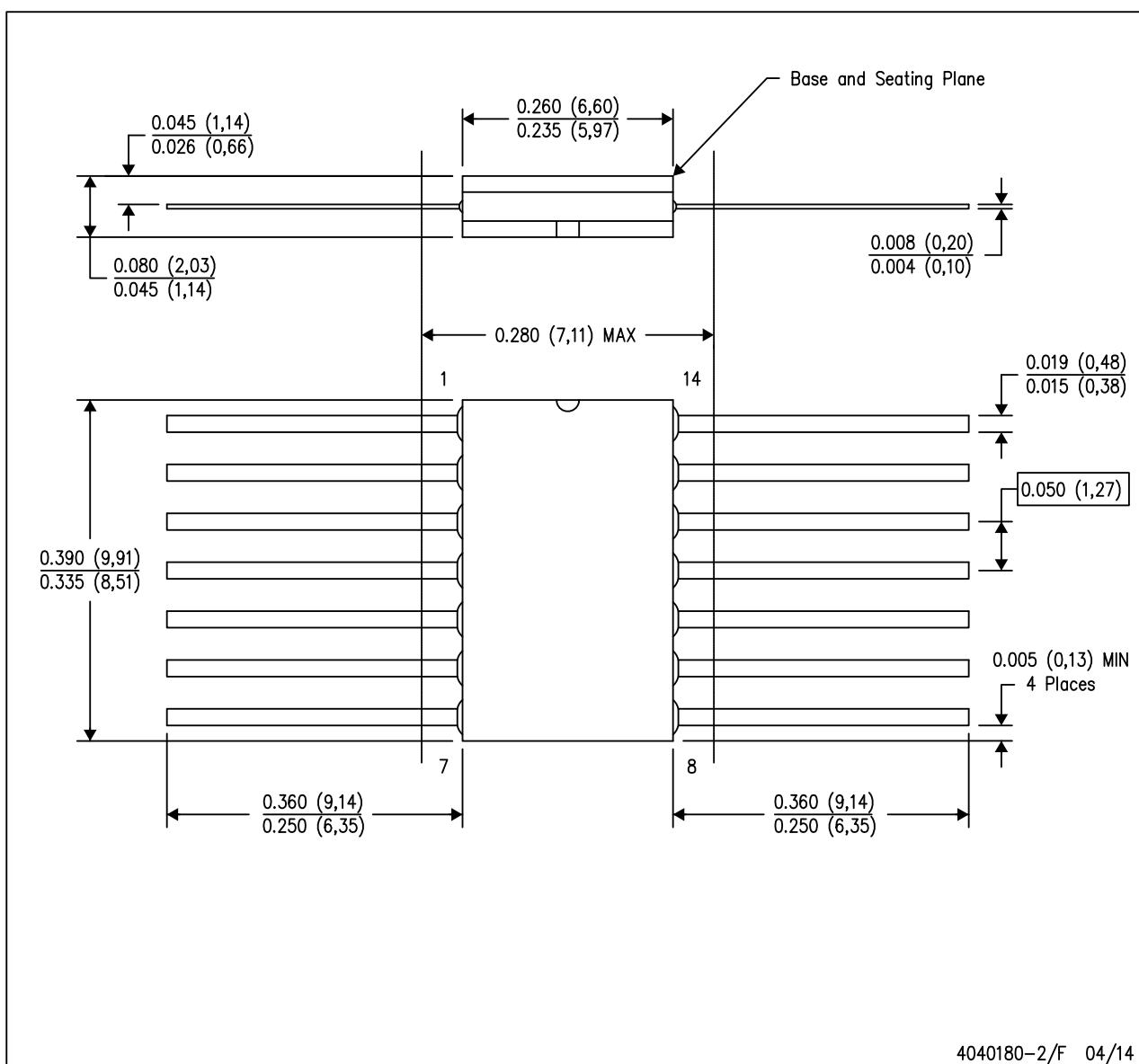
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

MECHANICAL DATA

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



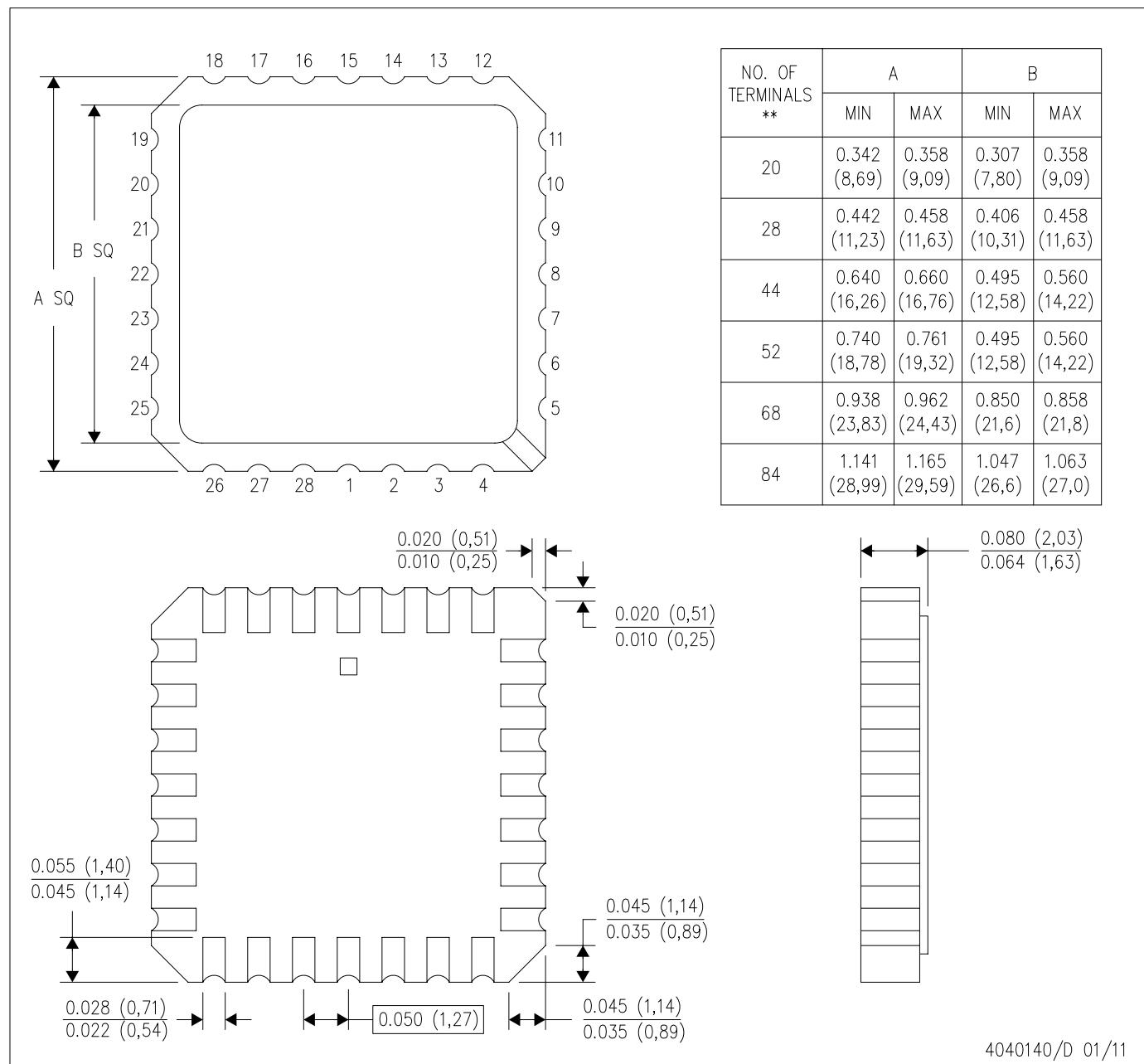
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL-STD-1835 GDFP1-F14

FK (S-CQCC-N)**

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package can be hermetically sealed with a metal lid.
 D. Falls within JEDEC MS-004

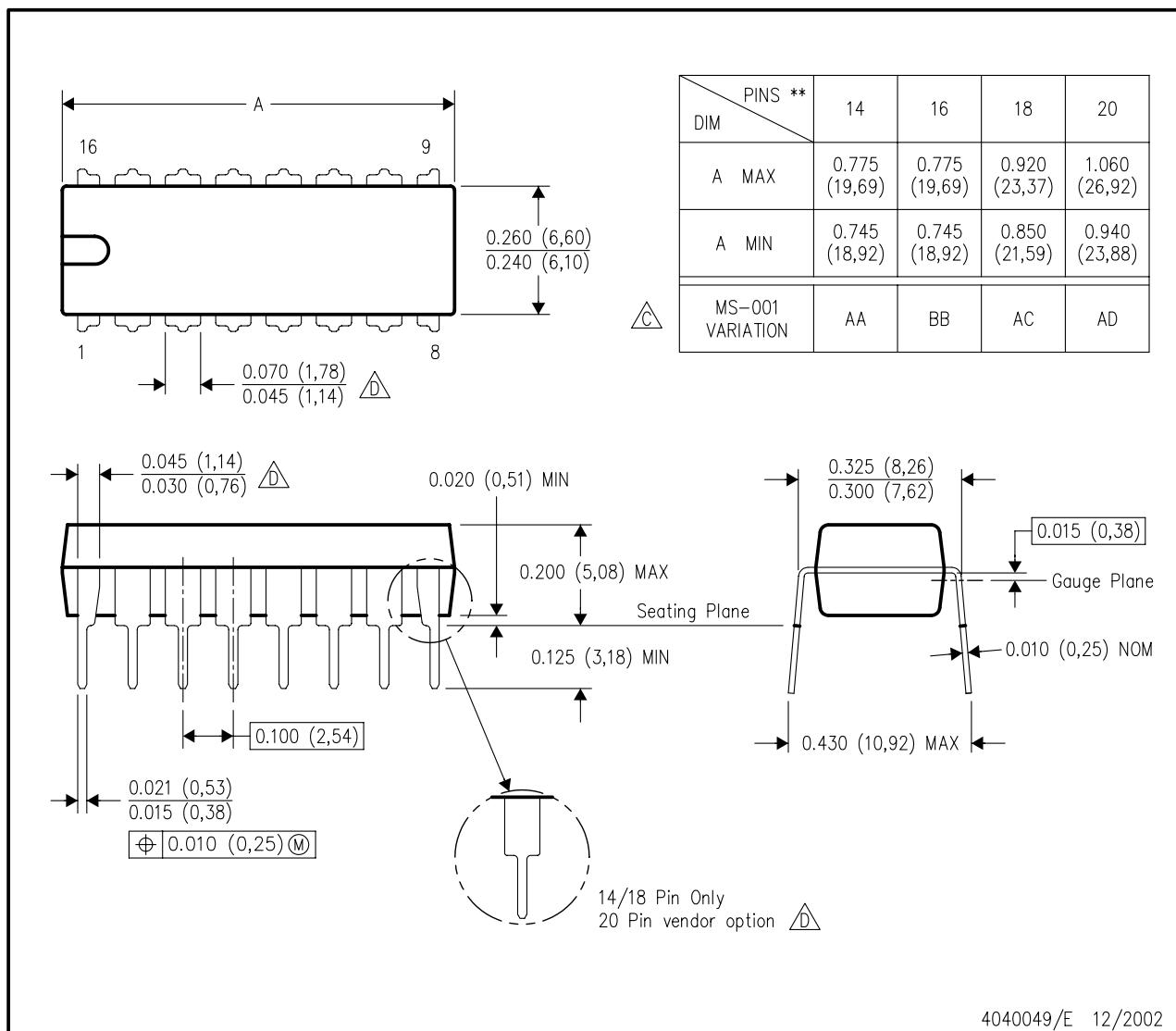
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MECHANICAL DATA

N (R-PDIP-T**)

16 PINS SHOWN

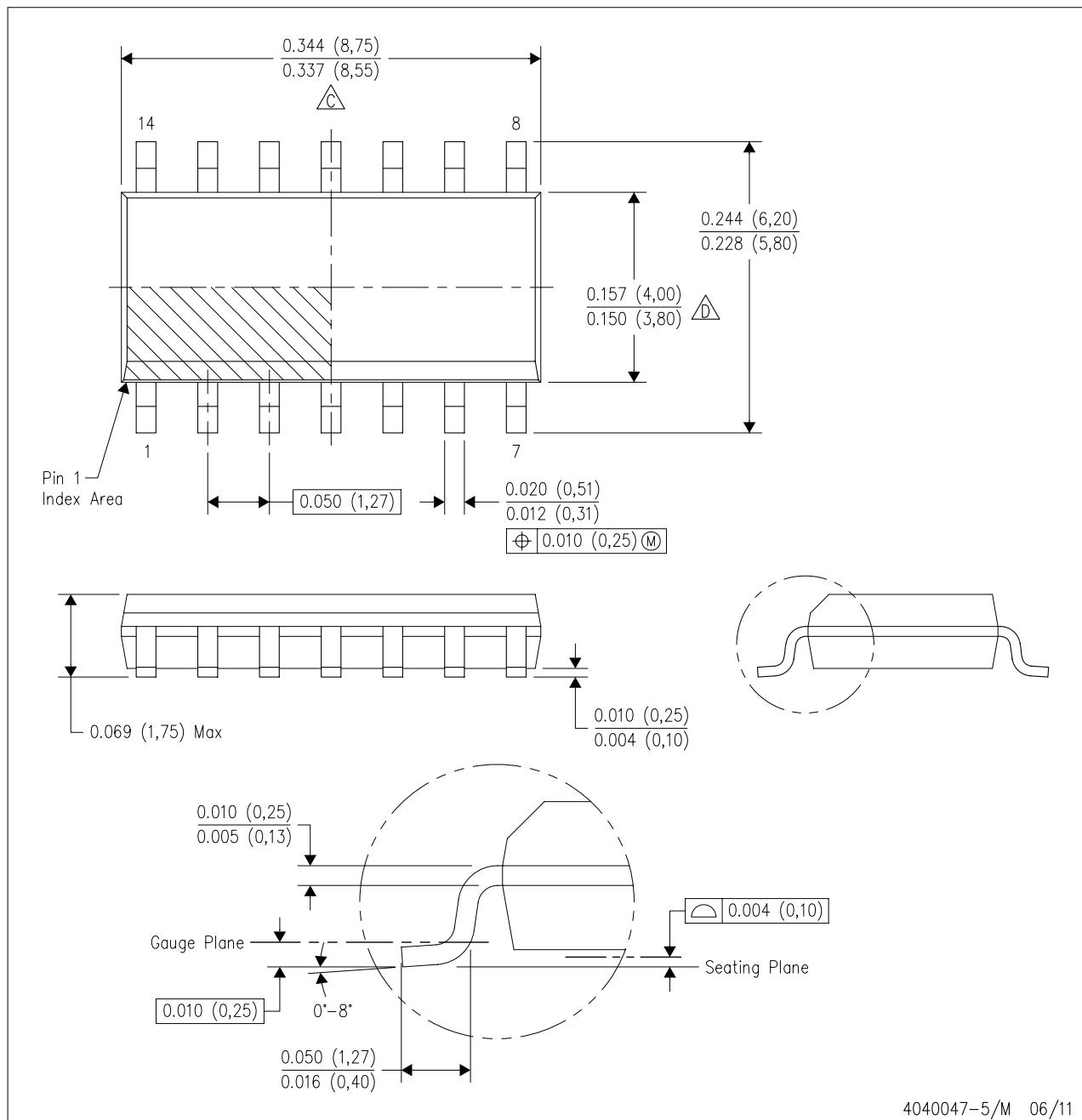
PLASTIC DUAL-IN-LINE PACKAGE



MECHANICAL DATA

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4040047-5/M 06/11

NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.

C Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.

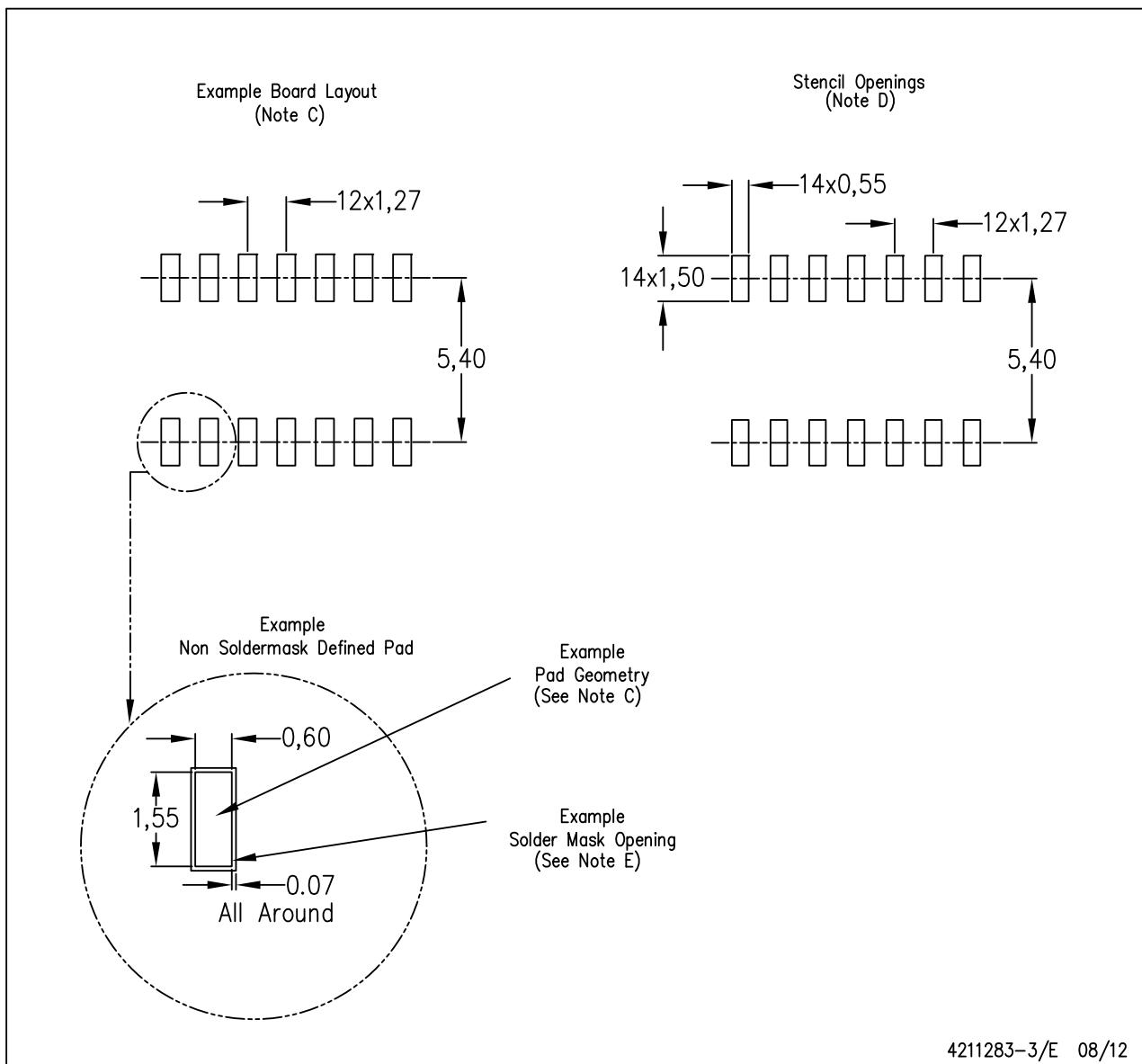
D Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.

E Reference JEDEC MS-012 variation AB.

LAND PATTERN DATA

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



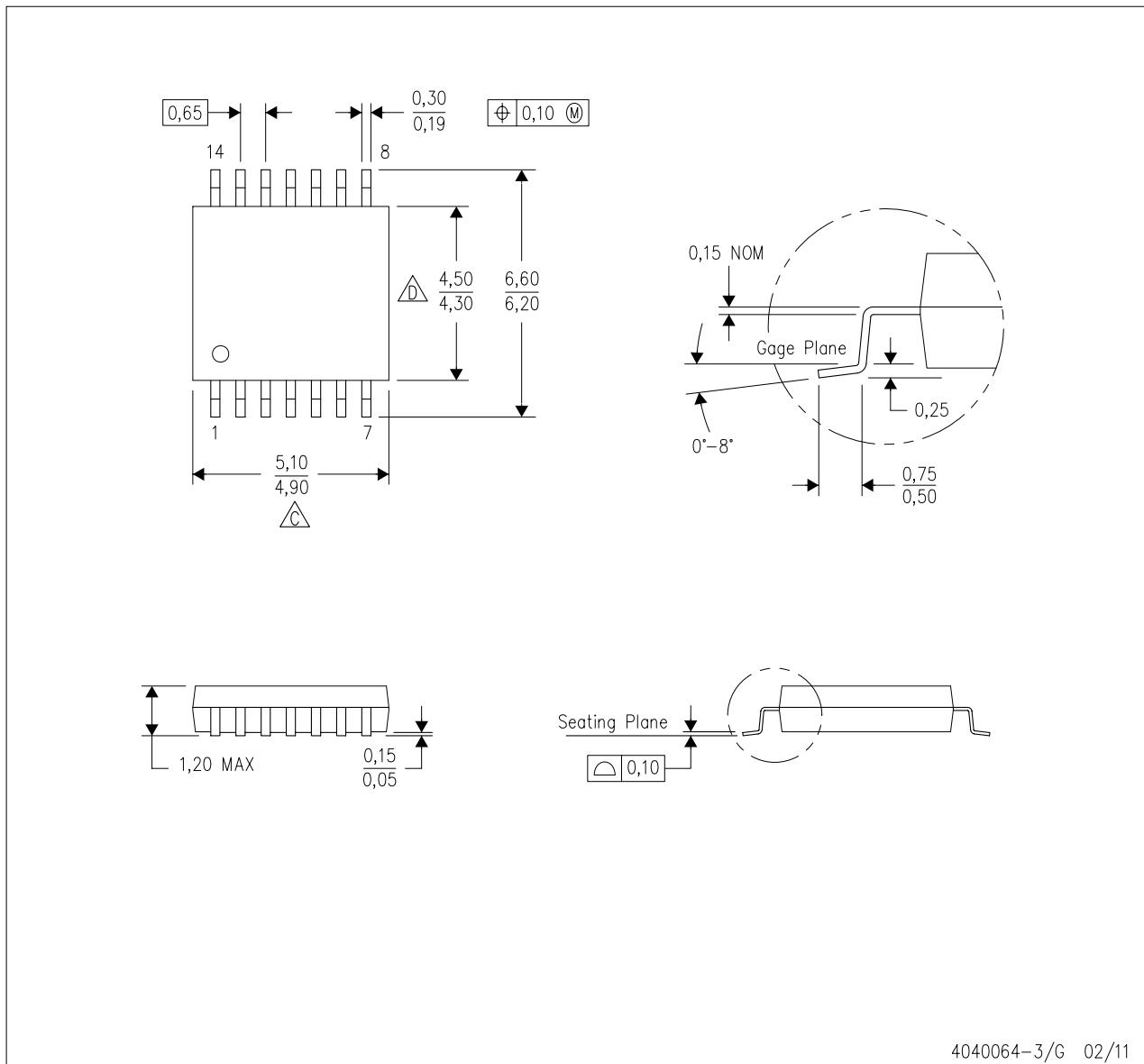
NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4040064-3/G 02/11

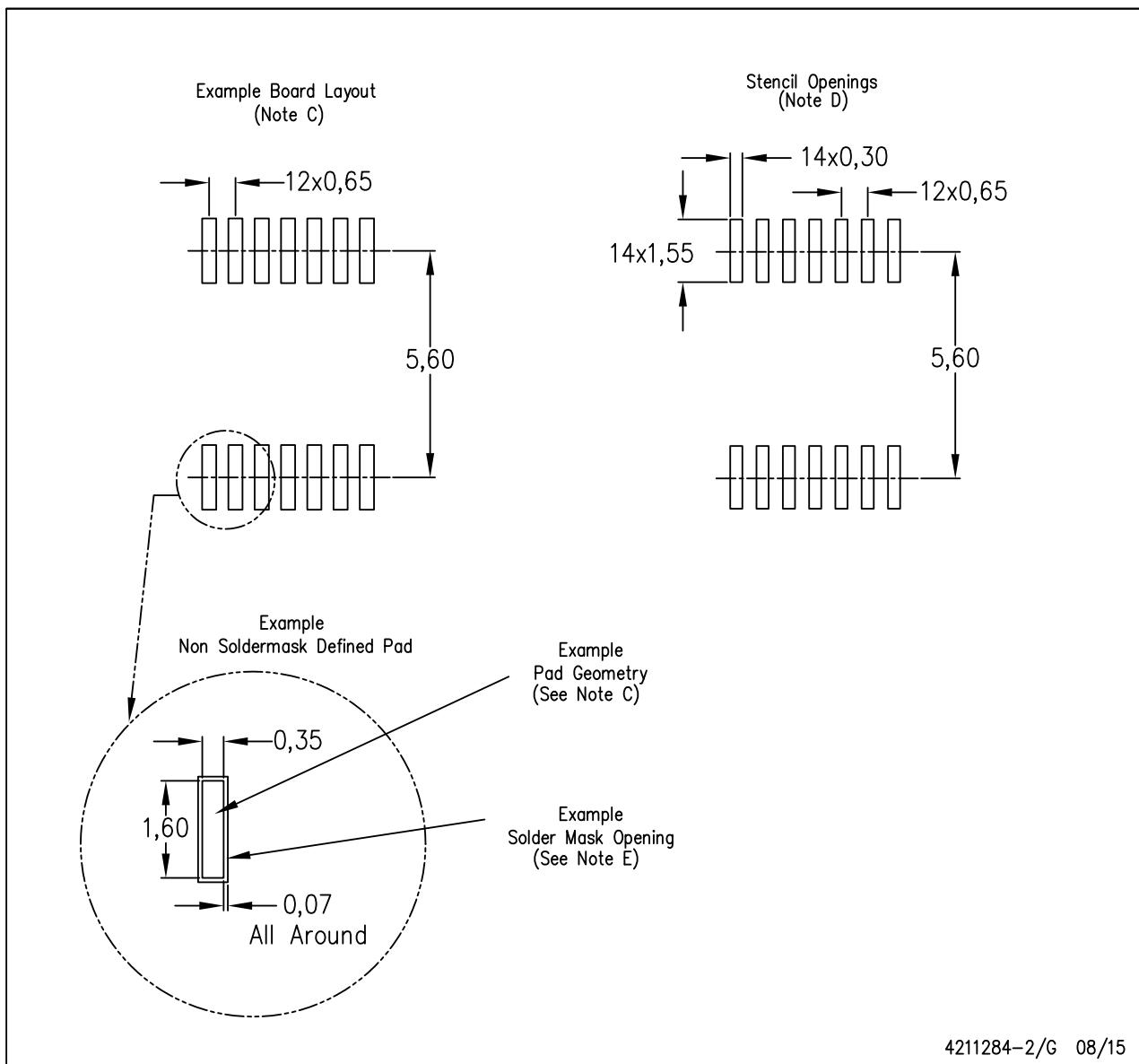
NOTES:

- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153

LAND PATTERN DATA

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4211284-2/G 08/15

NOTES:

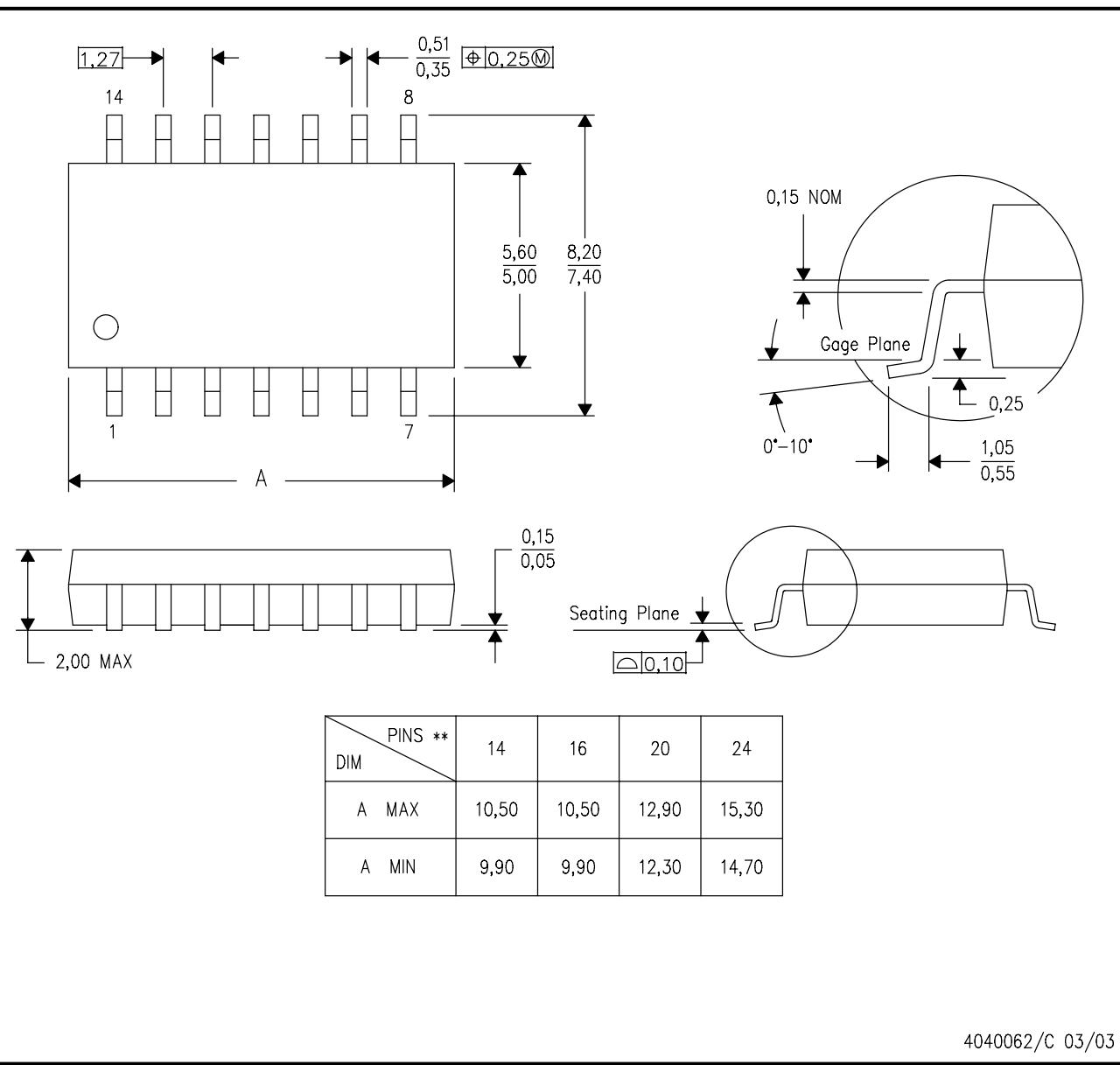
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

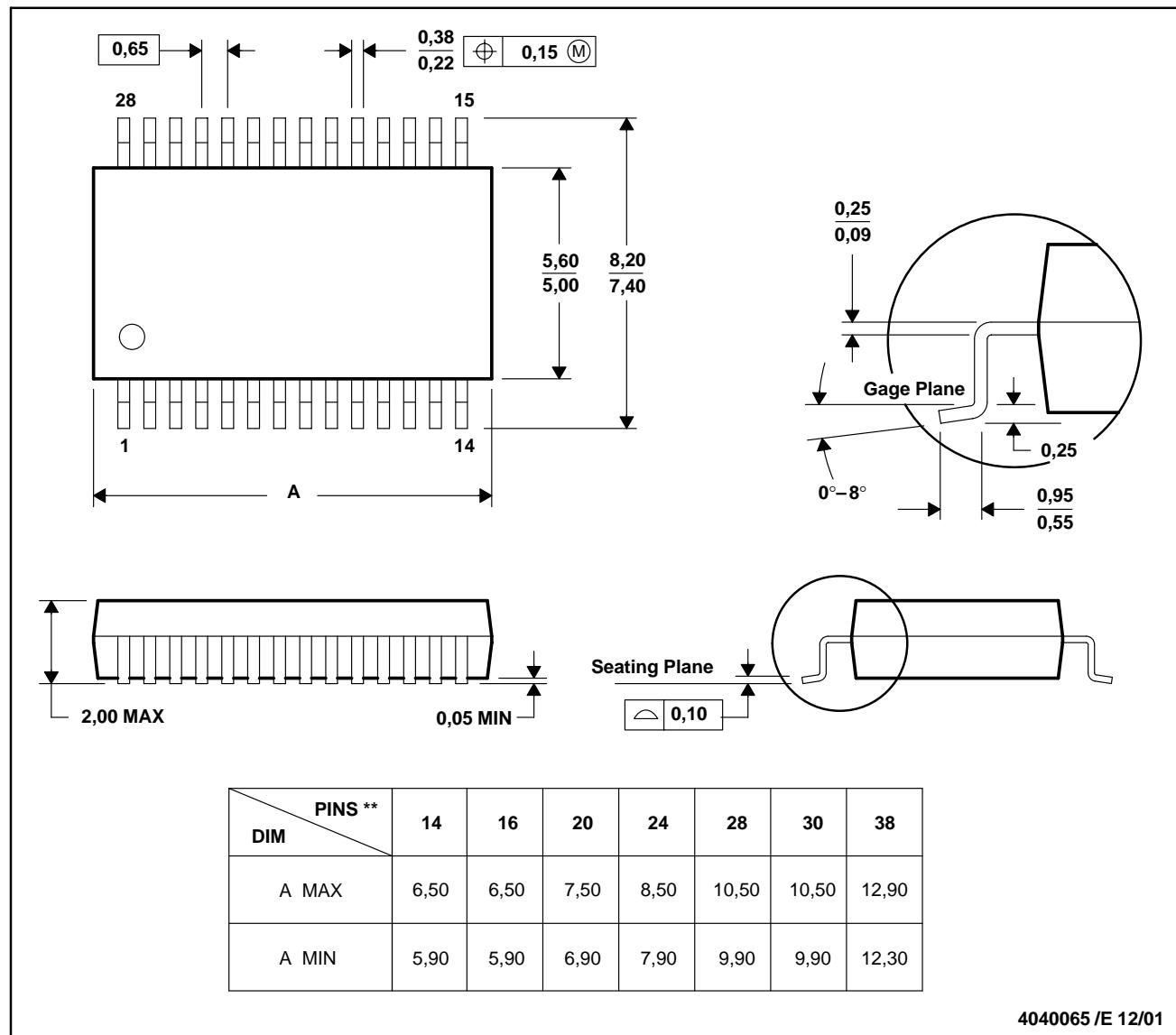
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

MSS002E – JANUARY 1995 – REVISED DECEMBER 2001

DB (R-PDSO-G)**

28 PINS SHOWN

PLASTIC SMALL-OUTLINE



4040065 /E 12/01

NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

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